



Spec No. :DS-55-92-0003 Effective Date: 08/23/2024

Revision: B

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



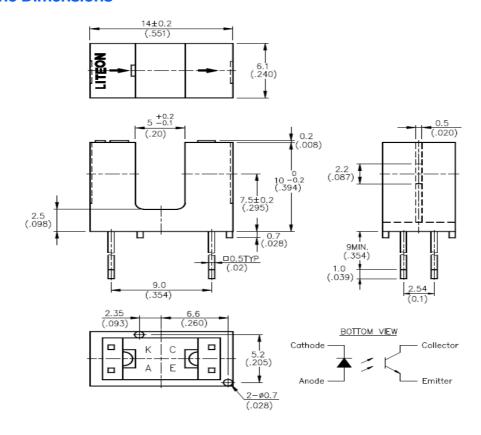
1. Description

Photointerrupters consist of infrared emitters and photo detectors in slotted, reflective and actuator type switches. Featuring high reliability, accuracy and special custom-tailored devices to fulfill various sensor requirements such as facsimile machine, copy machine, printer, scanner··· etc. Our skilled team of specialists with engineering expertise is ready to offer fast support for the requirements of custom-made parts and co-development with customers.

1. 1. Features

- NON-Contact Switching
- For Direct Pc Board Or Dual-In-Line Socket Mounting
- Fast Switching Speed

2. Outline Dimensions



Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.25mm unless otherwise noted.





Parameter	Maximum Rating	Unit	
INPUT LED			
Power Dissipation	80	mW	
Peak Forward Current (300 pps , 10 μ S pulse)	1	А	
Continuous Forward Current	50	mA	
Reverse Voltage	5	V	
OUTPUT PHOTOTRANSISTOR			
Power Dissipation	100	mW	
Collector-Emitter Voltage	30	V	
Emitter-Collector Voltage	5	V	
Collector Current	20	mA	
Operating Temperature Range	-25℃ to + 85℃		
Storage Temperature Range	-40℃ to + 100℃		
Lead Soldering Temperature [1.6mm (.063") From Case]	260°C for 5 Seconds		



4. Electrical / Optical Characteristics at TA=25 $^{\circ}$ C

Parame	eter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
INPUT LED							
Forward Voltage		VF	-	1.2	1.6	V	I _F = 20mA
Reverse Current		I_R	-	-	100	μA	$V_R = 5V$
OUTPUT PHOTOTRANSISTOR							
Collector-Emitter Dar	k Current	Iceo	-	-	100	nA	V _{CE} = 10V
Collector-Emitter Vol	tage	BV _{CEO}	30	-	-	V	I _{CE} =1mA
Emitter-Collector Vol	tage	BV _{ECO}	5	-	-	V	I _{EC} =100uA
COUPLER							
Collector Emitter Sat	uration Voltage	V _{CE(SAT)}	-	-	0.4	V	$I_C = 0.25 \text{mA}$ $I_F = 20 \text{mA}$
On State Collector C	urrent	I _{C(ON)}	0. 6	-	-	mA	$V_{CE} = 5V$ $I_F = 20mA$
Response Time	Rise Time	Tr	-	3	15	μS	RL=100 Ω , F=10KHZ,
	Fall Time	Tf	-	4	20		Ic=2mA, Vce=5V

NOTE:

^{1.} Forward voltage of tolerance \pm /-0.1V; Others of tolerance \pm 10%.



5. Typical Electrical / Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

Fig.1 Power Dissipation vs.

Ambient Temperature

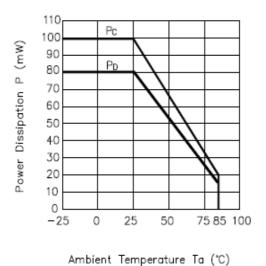
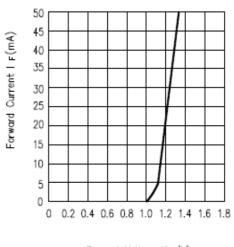


Fig.2 Forward Current vs. Forward Voltage



Forward Voltage V F (V)

Fig.3 Collector Current vs. Forward Current

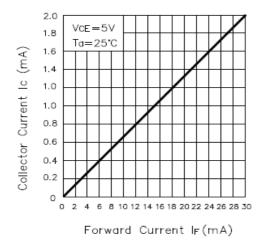


Fig.4 Cllector Current Ratio vs. Collector—emitter Voltage

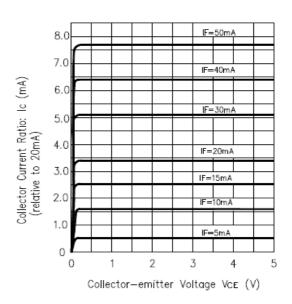




Fig.5 Relative output vs.
Ambient Temperature

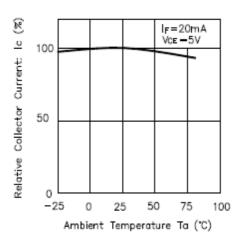


Fig.6 Collector—emitter Saturation Voltage vs. Ambient Temperature

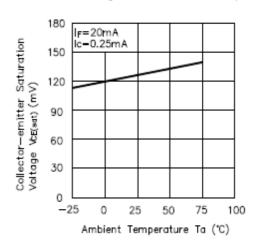
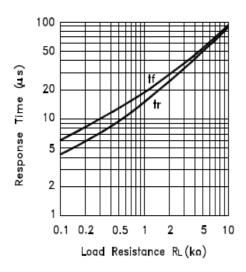
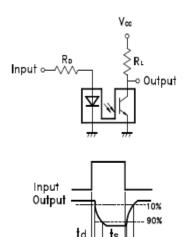


Fig.7 Response Time vs. Load Resistance



Test Circuit for Response Time





6. Soldering information

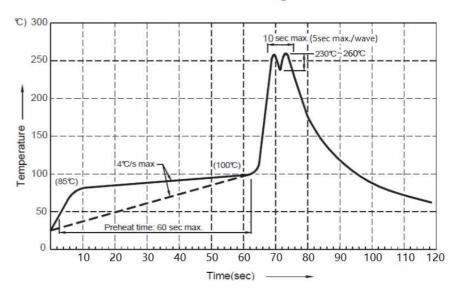
Dipping the housing into the solder must be avoided.

Do not apply any external stress to the lead frame during soldering while the product is at high temperature.

Recommended soldering conditions:

Lead Soldering		Wave soldering		
Temperature Soldering time Position	350°C Max. 3 seconds Max. (one time only) No closer than 2mm from the base of the housing	Pre-heat Pre-heat time Solder wave Soldering time Dipping Position	100℃ Max. 60 seconds Max. 260℃ Max. 5 seconds Max. No lower than 2mm from the base of the housing	

Recommended Wave soldering Profile:



7. Cautions for Storage

The storage ambient for this component should be <30°C temperature and < 70 % relative humidity, also the component should be assembled within 3 months upon the delivery date. To extend the storage life when the part still in original packing, the component should be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient but not over a year; after opening the package, the component must be consumed within 3months under controlled environment of <25°C and <60%RH. Please avoid rapid transitions in ambient temperature, especially in high humidity environment where condensation can occur. If storage conditions do not meet above criteria, the component's pin may become oxidized then solderability assessment and re-sorting must be performed before use.